MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

PESD0402MS07-MS

Product specification





FEATURES

- Ultra-Low capacitance:0.05pF(typ.)
- Low leakage current(<10nA)
- Fast response time(<1ns)
- Bi-directional, single line protection
- IEC 61000-4-2 (ESD Air): 15kV
- IEC 61000-4-2 (ESD Contact): 8kV

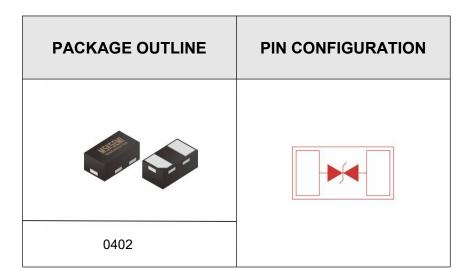
MACHANICAL DATA

- 0402
- Packaging: Tape and Reel
- Reel size: 7 inch
- 10000PCS/Reel

APPLICATIONS

- USB 3.0/3. 1
- HDMI 1.3/ 1.4/2.0
- RF Antenna
- SATA and eSATA Interface

Reference News





Limiting Values(TA = 25 °C, unless otherwise specified)

Symbol	Parameter	Conditions	Min	Max	Unit
Vesd	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	8	k _V
V 200		IEC 61000-4-2; Air Discharge	-	15	k _V
TA	Operating Temperature Range	-	-55	125	°C
T _{stg}	Storage Temperature Range	-	-40	85	°C

ELECTRICAL CHARACTERISTICS (Tamb=25℃)

Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
VDC	Continuous Operating Voltage	-	-	-	7	V
	Trigger Voltage	IEC61000-4-2 8kV		450		, ,
VT	Trigger Voltage	contact discharge	-	450	-	V
	Clamping Voltage	IEC61000-4-2 8kV				
VC	Olamping Voltago	contact discharge	-	40	-	V
_	Leakage Current	DC 7V shall be applied				_
IL	Leakage Cullell	on component	-	-	10	nA
CJ	Capacitance	Measured at 10MHz	-	0.05	-	p _F



Typical Characteristics

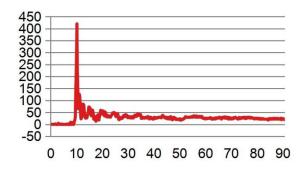


Fig. 1 Typical ESD Response (IEC 61000-4-2, 8kV contact discharge)

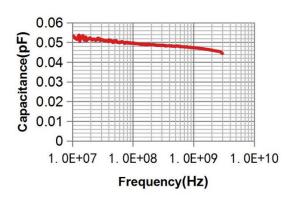


Fig.2 Typical Device Capacitance VS. Frequency

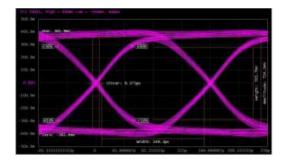
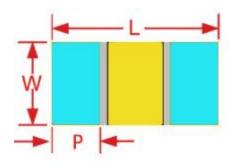


Fig.3 HDMI 2.0 Mask at 6.0 Gbps

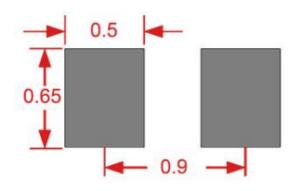


PACKAGE MECHANICAL DATA





Recommended Solder Pad Footprint



Notes:

This solder pad layout is for reference purposes only.

Dimension	Unit: Millimeters		
	Min	Max	
L	0.90	1. 10	
W	0.42	0.62	
р	0. 15	0.35	
Н	0.25	0.45	

REEL SPECIFICATION

P/N	PKG	QTY
PESD0402MS07-MS	0402	10000



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